

## Dual N-Ch 30V Fast Switching MOSFETs

### Description

The HSBB3214 is the high cell density trench N-ch MOSFETs, which provide excellent  $R_{DS(on)}$  and gate charge for most of the synchronous buck converter applications.

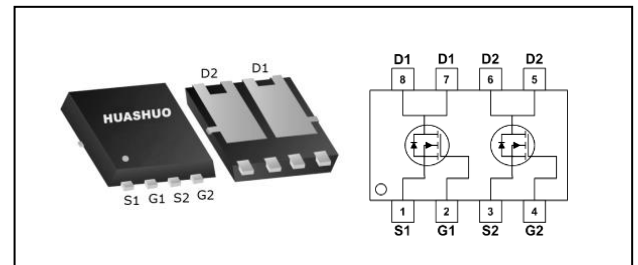
The HSBB3214 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent  $CdV/dt$  effect decline
- Advanced high cell density Trench technology

### Product Summary

$V_{DS}$	30	V
$R_{DS(ON),max}$	12	m $\Omega$
$I_D$	33	A

### PRPAK3\*3 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V_1$	33	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V_1$	16	A
$I_{DM}$	Pulsed Drain Current <sub>2</sub>	65	A
EAS	Single Pulse Avalanche Energy <sub>3</sub>	24.2	mJ
$I_{AS}$	Avalanche Current	22	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sub>4</sub>	26	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sub>1</sub>	---	75	$^\circ C/W$
$R_{\theta JL}$	Thermal Resistance Junction-Case <sub>1</sub>	---	8	$^\circ C/W$



**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.023	---	V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sub>2</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =15A	---	---	12	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	---	---	18	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	---	2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-5.08	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =15A	---	24	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	1.8	---	Ω
Q <sub>g</sub>	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =8A	---	9.63	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	3.88	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	3.44	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =15V, V <sub>GS</sub> =10V, R <sub>G</sub> =1.5Ω I <sub>D</sub> =8A	---	4.2	---	ns
T <sub>r</sub>	Rise Time		---	8.2	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	31	---	
T <sub>f</sub>	Fall Time		---	4	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	760	940	1175	pF
C <sub>oss</sub>	Output Capacitance		92	131	163	
C <sub>rss</sub>	Reverse Transfer Capacitance		76	109	153	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sub>1,5</sub>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	33	A
V <sub>SD</sub>	Diode Forward Voltage <sub>2</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =8A, di/dt=100A/μs, T <sub>J</sub> =25°C	---	8	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge		---	2.9	---	nC

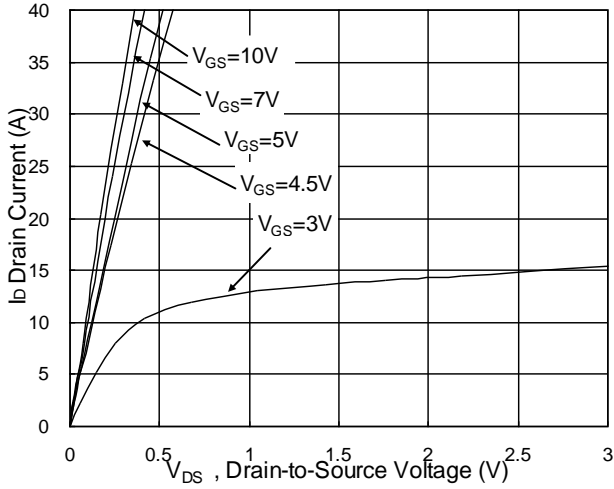
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=22A
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

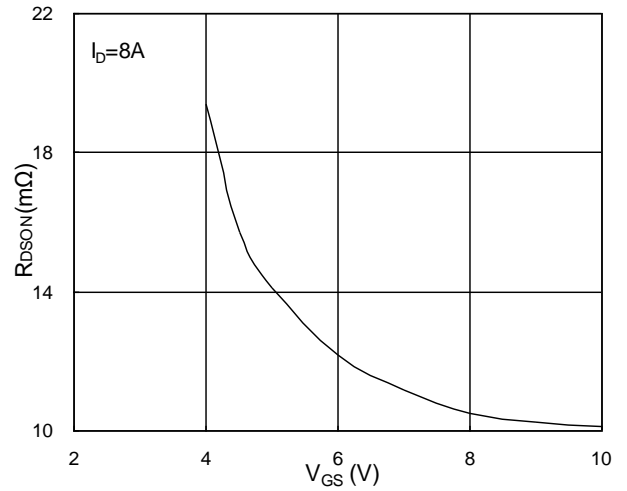


**Dual N-Ch 30V Fast Switching MOSFETs**

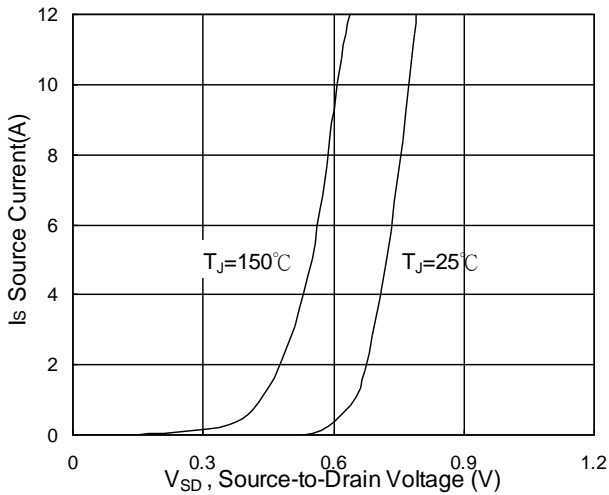
**Typical Characteristics**



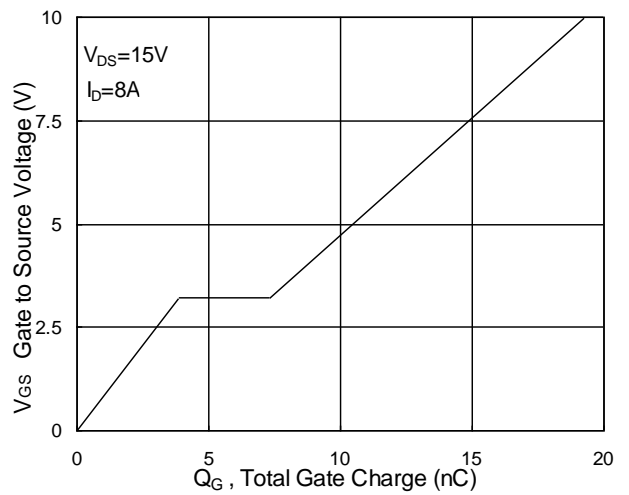
**Fig.1 Typical Output Characteristics**



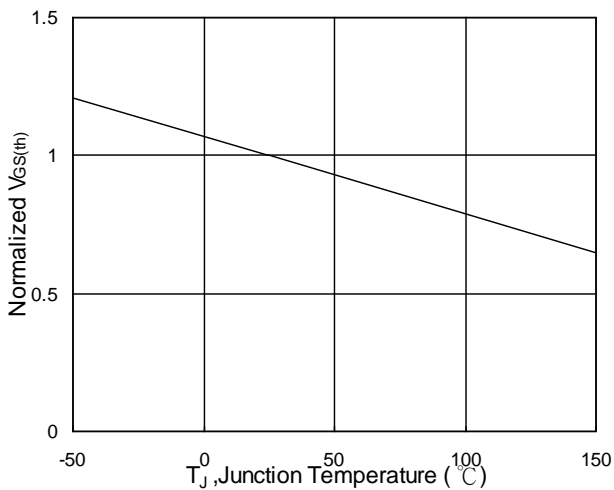
**Fig.2 On-Resistance vs. G-S Voltage**



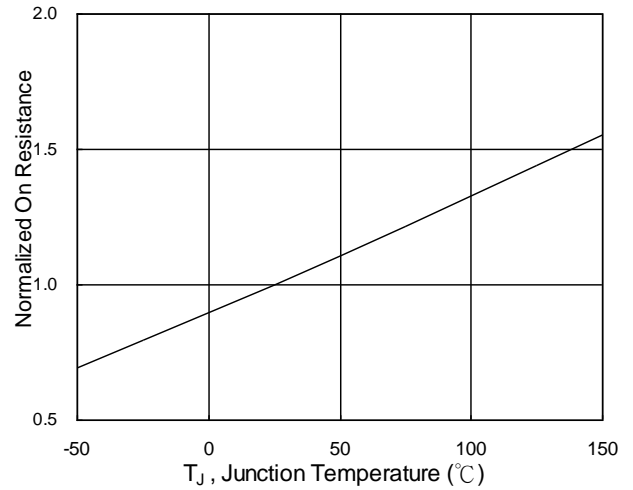
**Fig.3 Source Drain Forward Characteristics**



**Fig.4 Gate-Charge Characteristics**



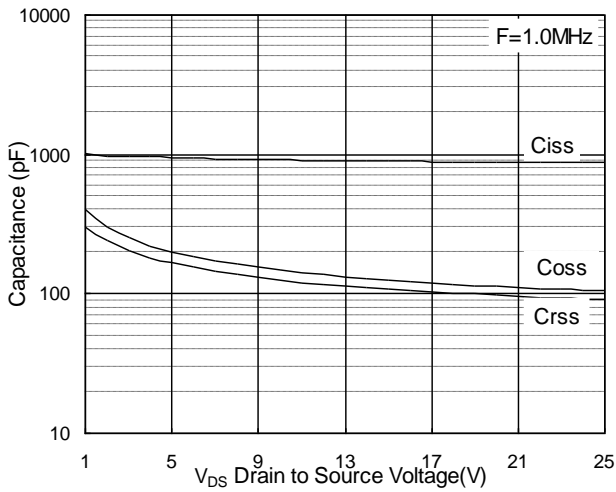
**Fig.5 Normalized VGS(th) vs. TJ**



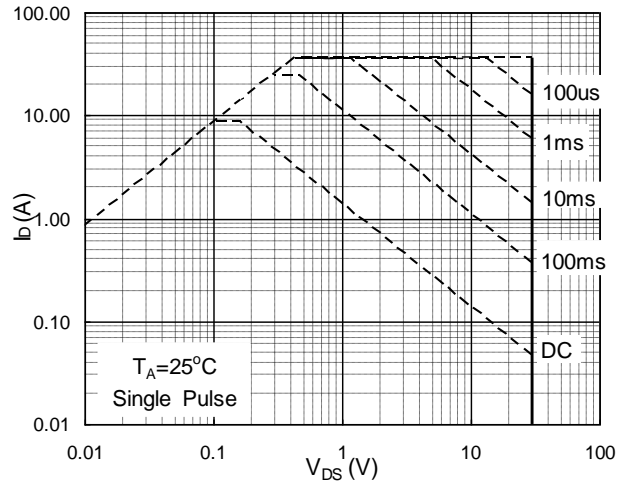
**Fig.6 Normalized RDS(on) vs. TJ**



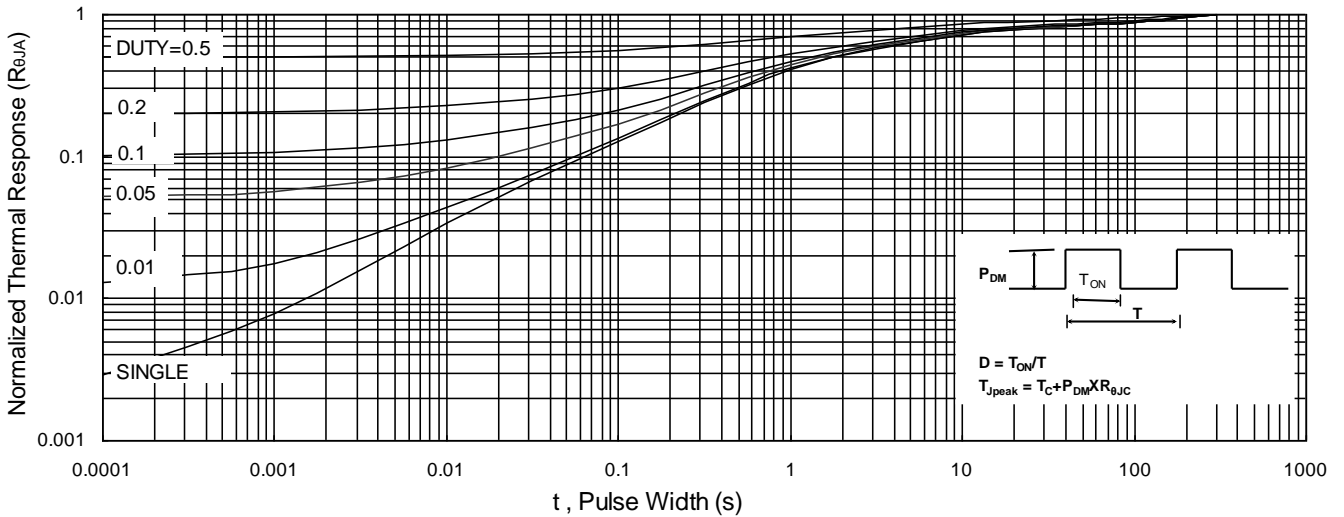
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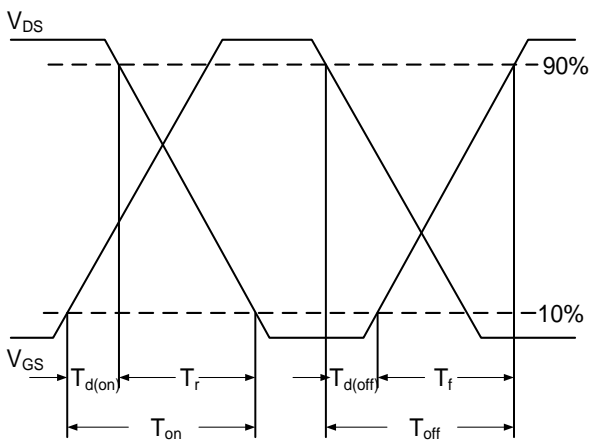
**Fig.7 Capacitance**



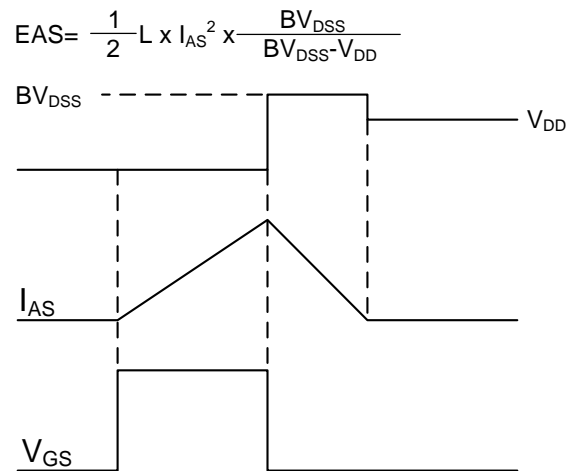
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



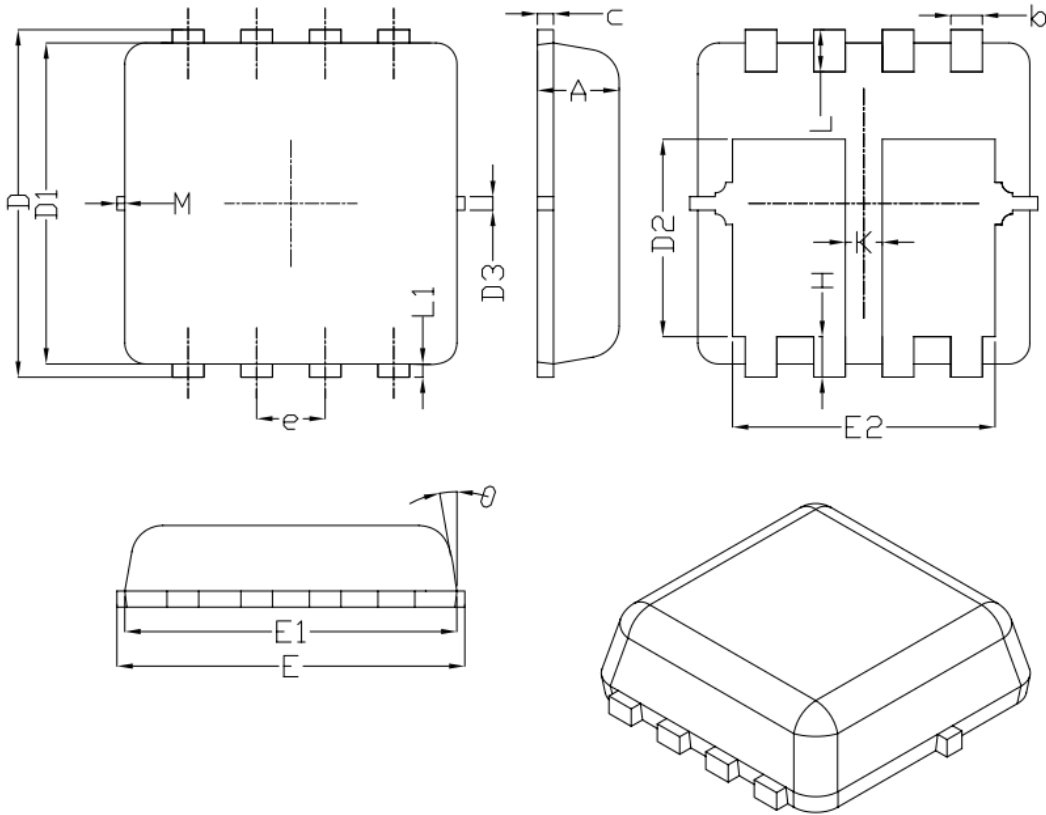
**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**



PRPAK3X3 Package Outline Dimensions



SYMBOL	DIMENSIONAL REQMTS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	---	0.13	---
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	---	0.13	---
K	0.30	---	---
θ	---	10°	12°
M	*	*	0.15
* Not specified			